

ABSTRACT OF THE DISCLOSURE

A first insulating film having openings is formed on a base made of, for example, copper. Wiring films made of a metallized film at lower portions are formed on the first insulating film. A second insulating film is formed thereon except for a certain portion, and then the base is selectively etched to expose the back surfaces of the wiring films. The wiring films and terminals such as ball electrodes are formed by electroplating. The base is connected to the wiring films to form a ground and/or power source line. In order to make it possible to mount an LSI chip on each main surface of the wiring substrate and to layer one another a plurality of wiring substrates each having the LSI chip mounted thereto, the wiring substrate is constructed such that the wiring films are formed on one side of the insulating resin film having openings and two kinds of metal bumps that are connected to the wiring films through the openings and are different in height from each other are formed on the other side.

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